

[52433/663]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of TERASHIMA, et al.

Serial No. Not Yet Assigned

Filing Date Herewith

Title SEMICONDUCTOR DEVICE AND METHOD TO PRODUCE
THE SAME

Handwritten signature and date: 1/15/02

PRELIMINARY AMENDMENT

Please amend the above-identified application as follows:

In the claims:

Please cancel claims 4-5, 7-9, 11, 13-15, and 20-21 without prejudice.

Please add the following new claims:

22. (New) A semiconductor device according to claim 1 characterized in that the bonding material and the reinforcing material consist of different materials.
23. (New) A semiconductor device according to claim 3 characterized in that the bonding material and the reinforcing material consist of different materials.
24. (New) A semiconductor device according to claim 1 characterized in that the reinforcing material consists of a metal and/or an inorganic material and the reinforcement covers the wire or a joint bulb with any of the metal coating and the inorganic material coating.
25. (New) A semiconductor device according to claim 3 characterized in that the reinforcing material consists of a metal and/or an inorganic material and the reinforcement covers the wire or a joint bulb with any of the metal coating and the inorganic material coating.
26. (New) A semiconductor device according to claim 1 characterized by forming, at the interface between the metal coating and the metal surface of the bonding wire, a diffusion layer of the two metals.
27. (New) A semiconductor device according to claim 3 characterized by forming, at the interface between the metal coating and the metal surface of the bonding wire, a diffusion layer of the two metals.
28. (New) A semiconductor device according to claim 1 characterized in that the bonding wire consists of any one of gold, copper, aluminum, silver and an alloy of any of these metals.
29. (New) A semiconductor device according to claim 3 characterized in that the bonding wire consists of any one of gold, copper, aluminum, silver and an alloy of any of these metals.

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